# 74HC595; 74HCT595

8-bit serial-in, serial or parallel-out shift register with output latches; 3-state

Rev. 6 — 12 December 2011

**Product data sheet** 

### 1. General description

The 74HC595; 74HCT595 are high-speed Si-gate CMOS devices and are pin compatible with Low-power Schottky TTL (LSTTL). They are specified in compliance with JEDEC standard No. 7A.

The 74HC595; 74HCT595 are 8-stage serial shift registers with a storage register and 3-state outputs. The registers have separate clocks.

Data is shifted on the positive-going transitions of the shift register clock input (SHCP). The data in each register is transferred to the storage register on a positive-going transition of the storage register clock input (STCP). If both clocks are connected together, the shift register will always be one clock pulse ahead of the storage register.

The shift register has a serial input (DS) and a serial standard output (Q7S) for cascading. It is also provided with asynchronous reset (active LOW) for all 8 shift register stages. The storage register has 8 parallel 3-state bus driver outputs. Data in the storage register appears at the output whenever the output enable input (OE) is LOW.

### 2. Features and benefits

- 8-bit serial input
- 8-bit serial or parallel output
- Storage register with 3-state outputs
- Shift register with direct clear
- 100 MHz (typical) shift out frequency
- ESD protection:
  - HBM JESD22-A114F exceeds 2000 V
  - MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from -40 °C to +85 °C and from -40 °C to +125 °C

# 3. Applications

- Serial-to-parallel data conversion
- Remote control holding register

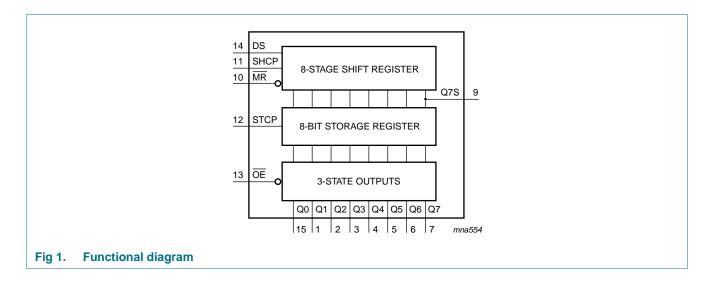


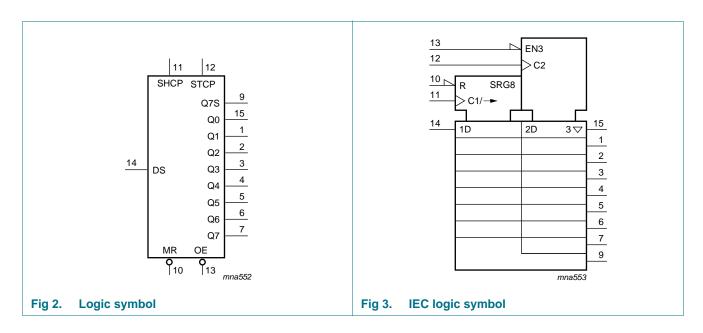
# 4. Ordering information

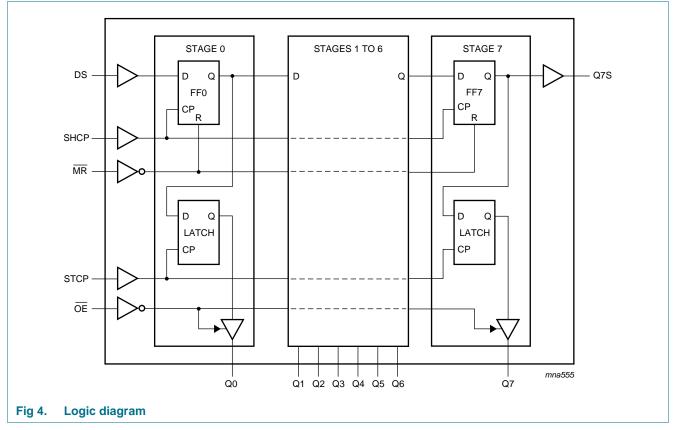
Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC595N	–40 °C to +125 °C	DIP16	plastic dual in-line package; 16 leads (300 mil)	SOT38-4
74HCT595N				
74HC595D	–40 °C to +125 °C	SO16	plastic small outline package; 16 leads;	SOT109-1
74HCT595D			body width 3.9 mm	
74HC595DB	–40 °C to +125 °C	SSOP16	plastic shrink small outline package; 16 leads;	SOT338-1
74HCT595DB			body width 5.3 mm	
74HC595PW	–40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads;	SOT403-1
74HCT595PW			body width 4.4 mm	
74HC595BQ	–40 °C to +125 °C	DHVQFN16	plastic dual in-line compatible thermal enhanced	SOT763-1
74HCT595BQ			very thin quad flat package; no leads; 16 terminals; body $2.5 \times 3.5 \times 0.85$ mm	

# 5. Functional diagram

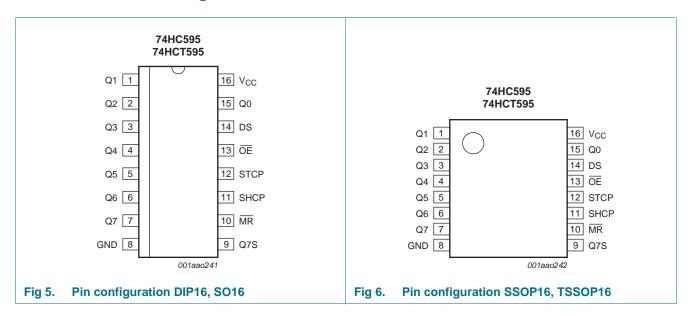


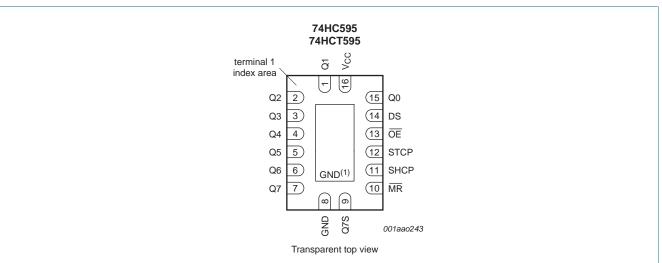




# 6. Pinning information

#### 6.1 Pinning





(1) This is not a supply pin, the substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad however if it is soldered the solder land should remain floating or be connected to GND.

Fig 7. Pin configuration for DHVQFN16

### 6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
Q1	1	parallel data output 1
Q2	2	parallel data output 2
Q3	3	parallel data output 3
Q4	4	parallel data output 4
Q5	5	parallel data output 5
Q6	6	parallel data output 6
Q7	7	parallel data output 7
GND	8	ground (0 V)
Q7S	9	serial data output
MR	10	master reset (active LOW)
SHCP	11	shift register clock input
STCP	12	storage register clock input
ŌĒ	13	output enable input (active LOW)
DS	14	serial data input
Q0	15	parallel data output 0
$V_{CC}$	16	supply voltage

# 7. Functional description

Table 3. Function table[1]

Contro	ol			Input	Outpu	t	Function
SHCP	STCP	OE	MR	DS	Q7S	Qn	
Χ	Χ	L	L	X	L	NC	a LOW-level on MR only affects the shift registers
Χ	<b>↑</b>	L	L	X	L	L	empty shift register loaded into storage register
Χ	Χ	Н	L	X	L	Z	shift register clear; parallel outputs in high-impedance OFF-state
<b>↑</b>	X	L	Н	Н	Q6S	NC	logic HIGH-level shifted into shift register stage 0. Contents of all shift register stages shifted through, e.g. previous state of stage 6 (internal Q6S) appears on the serial output (Q7S).
Χ	<b>↑</b>	L	Н	X	NC	QnS	contents of shift register stages (internal QnS) are transferred to the storage register and parallel output stages
<b>↑</b>	<b>↑</b>	L	Н	X	Q6S	QnS	contents of shift register shifted through; previous contents of the shift register is transferred to the storage register and the parallel output stages

<sup>[1]</sup> H = HIGH voltage state;

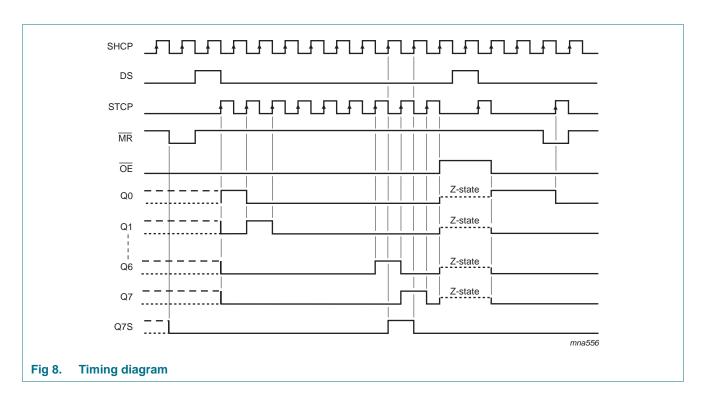
L = LOW voltage state;

 $<sup>\</sup>uparrow$  = LOW-to-HIGH transition;

X = don't care;

NC = no change;

Z = high-impedance OFF-state.



#### **Limiting values** 8.

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

					-
Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7	V
I <sub>IK</sub>	input clamping current	$V_I < -0.5 \text{ V or } V_I > V_{CC} + 0.5 \text{ V}$	-	±20	mA
I <sub>OK</sub>	output clamping current	$V_O < -0.5 \text{ V or } V_O > V_{CC} + 0.5 \text{ V}$	-	±20	mA
I <sub>O</sub>	output current	$V_{O} = -0.5 \text{ V to } (V_{CC} + 0.5 \text{ V})$			
		pin Q7S	-	±25	mA
		pins Qn	-	±35	mA
I <sub>CC</sub>	supply current		-	70	mA
I <sub>GND</sub>	ground current		-70	-	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>tot</sub>	total power dissipation				
	DIP16 package		<u>[1]</u> -	750	mW
	SO16 package		[2] _	500	mW
	SSOP16 package		[3] _	500	mW
	TSSOP16 package		[3] _	500	mW
	DHVQFN16 package		<u>[4]</u> -	500	mW

<sup>[1]</sup> For DIP16 package: Ptot derates linearly with 12 mW/K above 70 °C.

74HC\_HCT595

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For SO16 package: Ptot derates linearly with 8 mW/K above 70 °C.

For SSOP16 and TSSOP16 packages:  $P_{tot}$  derates linearly with 5.5 mW/K above 60 °C.

For DHVQFN16 package: Ptot derates linearly with 4.5 mW/K above 60 °C.

# 9. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	7	74HC59	5	7	4HCT59	)5	Unit
			Min	Тур	Max	Min	Тур	Max	
$V_{CC}$	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
VI	input voltage		0	-	$V_{CC}$	0	-	$V_{CC}$	V
Vo	output voltage		0	-	$V_{CC}$	0	-	$V_{CC}$	V
$\Delta t/\Delta V$	input transition rise and	$V_{CC} = 2.0 \text{ V}$	-	-	625	-	-	-	ns/V
	fall rate	V <sub>CC</sub> = 4.5 V	-	1.67	139	-	1.67	139	ns/V
		$V_{CC} = 6.0 \text{ V}$	-	-	83	-	-	-	ns/V
T <sub>amb</sub>	ambient temperature		-40	+25	+125	-40	+25	+125	°C

### 10. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40	°C to +8	5 °C	-40 °C to	+125 °C	Unit
			Min	Тур	Max	Min	Max	
74HC595	'		'					
$V_{IH}$	HIGH-level	V <sub>CC</sub> = 2.0 V	1.5	1.2	-	1.5	-	V
	input voltage	V <sub>CC</sub> = 4.5 V	3.15	2.4	-	3.15	-	V
		V <sub>CC</sub> = 6.0 V	4.2	3.2	-	4.2	-	V
$V_{IL}$	LOW-level	V <sub>CC</sub> = 2.0 V	-	0.8	0.5	-	0.5	V
	input voltage	V <sub>CC</sub> = 4.5 V	-	2.1	1.35	-	1.35	V
		V <sub>CC</sub> = 6.0 V	-	2.8	1.8	-	1.8	V
V <sub>OH</sub>	HIGH-level	$V_I = V_{IH}$ or $V_{IL}$						
	output voltage	all outputs						
		$I_O = -20 \mu A; V_{CC} = 2.0 V$	1.9	2.0	-	1.9	-	V
		$I_O = -20 \mu A; V_{CC} = 4.5 V$	4.4	4.5	-	4.4	-	V
		$I_O = -20 \mu A; V_{CC} = 6.0 \text{ V}$	5.9	6.0	-	5.9	-	V
		Q7S output						
		$I_{O} = -4 \text{ mA}; V_{CC} = 4.5 \text{ V}$	3.84	4.32	-	3.7	-	V
		$I_{O} = -5.2 \text{ mA}; V_{CC} = 6.0 \text{ V}$	5.34	5.81	-	5.2	-	V
		Qn bus driver outputs						
		$I_{O} = -6 \text{ mA}; V_{CC} = 4.5 \text{ V}$	3.84	4.32	-	3.7	-	V
		$I_{O} = -7.8 \text{ mA}; V_{CC} = 6.0 \text{ V}$	5.34	5.81	-	5.2	-	V

 Table 6.
 Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40	°C to +8	5 °C	-40 °C to	o +125 °C	Unit
			Min	Тур	Max	Min	Max	
/ <sub>OL</sub>	LOW-level	$V_I = V_{IH}$ or $V_{IL}$				1		'
	output voltage	all outputs						
		$I_O = 20 \mu A; V_{CC} = 2.0 V$	-	0	0.1	-	0.1	V
		$I_O = 20 \mu A; V_{CC} = 4.5 V$	-	0	0.1	-	0.1	V
		$I_O = 20 \mu A; V_{CC} = 6.0 V$	-	0	0.1	-	0.1	V
		Q7S output						
		$I_{O} = 4 \text{ mA}; V_{CC} = 4.5 \text{ V}$	-	0.15	0.33	-	0.4	V
		$I_{O} = 5.2 \text{ mA}; V_{CC} = 6.0 \text{ V}$	-	0.16	0.33	-	0.4	V
		Qn bus driver outputs						
		$I_{O} = 6 \text{ mA}; V_{CC} = 4.5 \text{ V}$	-	0.15	0.33	-	0.4	V
		$I_{O} = 7.8 \text{ mA}; V_{CC} = 6.0 \text{ V}$	-	0.16	0.33	-	0.4	V
I	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 6.0 \text{ V}$	-	-	±1.0	-	±1.0	μА
OZ	OFF-state output current	$V_I = V_{IH}$ or $V_{IL}$ ; $V_{CC} = 6.0$ V; $V_O = V_{CC}$ or GND	-	-	±5.0	-	±10	μΑ
СС	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 6.0 \text{ V}$	-	-	80	-	160	μА
Ç <sub>i</sub>	input capacitance		-	3.5	-	-	-	pF
74HCT59		V 45.V4-55.V	0.0	4.0		0.0		
/ <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	V
/ <sub>IL</sub>	LOW-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	-	1.2	8.0	-	0.8	V
/ <sub>OH</sub>	HIGH-level	$V_I = V_{IH}$ or $V_{IL}$ ; $V_{CC} = 4.5 \text{ V}$						
	output voltage	all outputs						
		$I_{O} = -20 \mu A$	4.4	4.5	-	4.4	-	V
		Q7S output						
		$I_O = -4 \text{ mA}$	3.84	4.32	-	3.7	-	V
		Qn bus driver outputs						
		$I_O = -6 \text{ mA}$	3.7	4.32	-	3.7	-	V
/ <sub>OL</sub>	LOW-level	$V_I = V_{IH}$ or $V_{IL}$ ; $V_{CC} = 4.5 \text{ V}$						
	output voltage	all outputs						
		I <sub>O</sub> = 20 μA	-	0	0.1	-	0.1	V
		Q7S output						
		I <sub>O</sub> = 4.0 mA	-	0.15	0.33	-	0.4	V
		Qn bus driver outputs						
		I <sub>O</sub> = 6.0 mA	-	0.16	0.33	-	0.4	V
l	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 5.5 \text{ V}$	-	-	±1.0	-	±1.0	μΑ

 Table 6.
 Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40	°C to +8	5 °C	–40 °C to	+125 °C	Unit
			Min	Тур	Max	Min	Max	
l <sub>OZ</sub>	OFF-state output current	$V_I = V_{IH}$ or $V_{IL}$ ; $V_{CC} = 5.5$ V; $V_O = V_{CC}$ or GND	-	-	±5.0	-	±10	μΑ
I <sub>CC</sub>	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 5.5 \text{ V}$	-	-	80	-	160	μΑ
$\Delta I_{CC}$	additional supply current	per input pin; $I_O = 0$ A; $V_I = V_{CC} - 2.1$ V; other inputs at $V_{CC}$ or GND; $V_{CC} = 4.5$ V to 5.5 V						
		pins MR, SHCP, STCP, OE	-	150	675	-	735	μΑ
		pin DS	-	25	113	-	123	μΑ
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	pF

# 11. Dynamic characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit see Figure 14.

Symbol	Parameter	Conditions			25 °C		-40 °C 1	to +85 °C	-40 °C t	o +125 °C	Unit
				Min	Typ[1]	Max	Min	Max	Min	Max	
74HC59	5								1		
t <sub>pd</sub>	propagation	SHCP to Q7S; see Figure 9	[2]								
	delay	V <sub>CC</sub> = 2 V		-	52	160	-	200	-	240	ns
		V <sub>CC</sub> = 4.5 V		-	19	32	-	40	-	48	ns
		V <sub>CC</sub> = 6 V		-	15	27	-	34	-	41	ns
		STCP to Qn; see Figure 10	[2]								
		V <sub>CC</sub> = 2 V		-	55	175	-	220	-	265	ns
		V <sub>CC</sub> = 4.5 V		-	20	35	-	44	-	53	ns
		V <sub>CC</sub> = 6 V		-	16	30	-	37	-	45	ns
		MR to Q7S; see Figure 12	[3]								
		V <sub>CC</sub> = 2 V		-	47	175	-	220	-	265	ns
		V <sub>CC</sub> = 4.5 V		-	17	35	-	44	-	53	ns
		V <sub>CC</sub> = 6 V		-	14	30	-	37	-	45	ns
t <sub>en</sub>	enable time	OE to Qn; see Figure 13	[4]								
		V <sub>CC</sub> = 2 V		-	47	150	-	190	-	225	ns
		V <sub>CC</sub> = 4.5 V		-	17	30	-	38	-	45	ns
		V <sub>CC</sub> = 6 V		-	14	26	-	33	-	38	ns
t <sub>dis</sub>	disable time	OE to Qn; see Figure 13	[5]								
		V <sub>CC</sub> = 2 V		-	41	150	-	190	-	225	ns
		$V_{CC} = 4.5 \text{ V}$		-	15	30	-	38	-	45	ns
		V <sub>CC</sub> = 6 V		-	12	27	-	33	-	38	ns
t <sub>W</sub>	pulse width	SHCP HIGH or LOW; see Figure 9									
		V <sub>CC</sub> = 2 V		75	17	-	95	-	110	-	ns
		V <sub>CC</sub> = 4.5 V		15	6	-	19	-	22	-	ns
		V <sub>CC</sub> = 6 V		13	5	-	16	-	19	-	ns
		STCP HIGH or LOW; see Figure 10									
		V <sub>CC</sub> = 2 V		75	11	-	95	-	110	-	ns
		V <sub>CC</sub> = 4.5 V		15	4	-	19	-	22	-	ns
		V <sub>CC</sub> = 6 V		13	3	-	16	-	19	-	ns
		MR LOW; see Figure 12									
		V <sub>CC</sub> = 2 V		75	17	-	95	-	110	-	ns
		V <sub>CC</sub> = 4.5 V		15	6	-	19	-	22	-	ns
		V <sub>CC</sub> = 6 V		13	5	-	16	-	19	-	ns

 Table 7.
 Dynamic characteristics ...continued

Voltages are referenced to GND (ground = 0 V); for test circuit see Figure 14.

Symbol	Parameter	Conditions			25 °C		-40 °C t	o +85 °C	-40 °C	to +125 °C	Uni
				Min	Typ[1]	Max	Min	Max	Min	Max	
su	set-up time	DS to SHCP; see Figure 10									
		V <sub>CC</sub> = 2 V		50	11	-	65	-	75	-	ns
		V <sub>CC</sub> = 4.5 V		10	4	-	13	-	15	-	ns
		V <sub>CC</sub> = 6 V		9	3	-	11	-	13	-	ns
		SHCP to STCP; see Figure 11									
		V <sub>CC</sub> = 2 V		75	22	-	95	-	110	-	ns
		V <sub>CC</sub> = 4.5 V		15	8	-	19	-	22	-	ns
		V <sub>CC</sub> = 6 V		13	7	-	16	-	19	-	ns
h	hold time	DS to SHCP; see Figure 11									
		V <sub>CC</sub> = 2 V		3	-6	-	3	-	3	-	ns
		V <sub>CC</sub> = 4.5 V		3	-2	-	3	-	3	-	ns
		V <sub>CC</sub> = 6 V		3	-2	-	3	-	3	-	ns
rec	recovery	MR to SHCP; see Figure 12									
	time	V <sub>CC</sub> = 2 V		50	-19	-	65	-	75	-	ns
		V <sub>CC</sub> = 4.5 V		10	-7	-	13	-	15	-	ns
		V <sub>CC</sub> = 6 V		9	-6	-	11	-	13	-	ns
max	maximum frequency	SHCP or STCP; see Figure 9 and 10									
		V <sub>CC</sub> = 2 V		9	30	-	4.8	-	4	-	МН
		V <sub>CC</sub> = 4.5 V		30	91	-	24	-	20	-	МН
		V <sub>CC</sub> = 6 V		35	108	-	28	-	24	-	МН
C <sub>PD</sub>	power dissipation capacitance	$f_i$ = 1 MHz; $V_I$ = GND to $V_{CC}$	[6][7]	-	115	-	-	-	-	-	pF
'4HCT5	95; V <sub>CC</sub> = 4.5	V to 5.5 V									
pd	propagation	SHCP to Q7S; see Figure 9	[2]	-	25	42	-	53	-	63	ns
	delay	STCP to Qn; see Figure 10	[2]	-	24	40	-	50	-	60	ns
		MR to Q7S; see Figure 12	[3]	-	23	40	-	50	-	60	ns
en	enable time	OE to Qn; see Figure 13	<u>[4]</u>	-	21	35	-	44	-	53	ns
dis	disable time	OE to Qn; see Figure 13	<u>[5]</u>	-	18	30	-	38	-	45	ns
W	pulse width	SHCP HIGH or LOW; see Figure 9		16	6	-	20	-	24	-	ns
		STCP HIGH or LOW; see Figure 10		16	5	-	20	-	24	-	ns
		MR LOW; see Figure 12		20	8	-	25	-	30	-	ns
su	set-up time	DS to SHCP; see Figure 10		16	5	-	20	-	24	-	ns
		SHCP to STCP; see Figure 11		16	8	-	20	-	24	-	ns
h	hold time	DS to SHCP; see Figure 11		3	-2	-	3	-	3	-	ns

 Table 7.
 Dynamic characteristics ...continued

Voltages are referenced to GND (ground = 0 V); for test circuit see Figure 14.

Symbol	Parameter	Conditions		25 °C		-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	Min	Max	
t <sub>rec</sub>	recovery time	MR to SHCP; see Figure 12	10	-7	-	13	-	15	-	ns
f <sub>max</sub>	maximum frequency	SHCP and STCP; see <u>Figure 9</u> and <u>10</u>	30	52	-	24	-	20	-	MHz
C <sub>PD</sub>	power dissipation capacitance	$f_i = 1 \text{ MHz}; V_I = \text{GND to } V_{CC}$ [6]	-	130	-	-	-	-	-	pF

- [1] Typical values are measured at nominal supply voltage.
- [2]  $t_{pd}$  is the same as  $t_{PHL}$  and  $t_{PLH}$ .
- [3] t<sub>pd</sub> is the same as t<sub>PHL</sub> only.
- [4] t<sub>en</sub> is the same as t<sub>PZL</sub> and t<sub>PZH</sub>.
- [5]  $t_{dis}$  is the same as  $t_{PLZ}$  and  $t_{PHZ}$ .
- [6]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu W$ ).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma (C_L \times V_{CC}^2 \times f_o)$$
 where:

 $f_i$  = input frequency in MHz;

f<sub>o</sub> = output frequency in MHz;

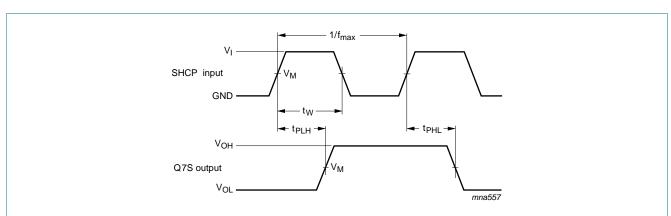
 $\Sigma(C_L \times V_{CC}^2 \times f_o)$  = sum of outputs;

C<sub>L</sub> = output load capacitance in pF;

 $V_{CC}$  = supply voltage in V.

[7] All 9 outputs switching.

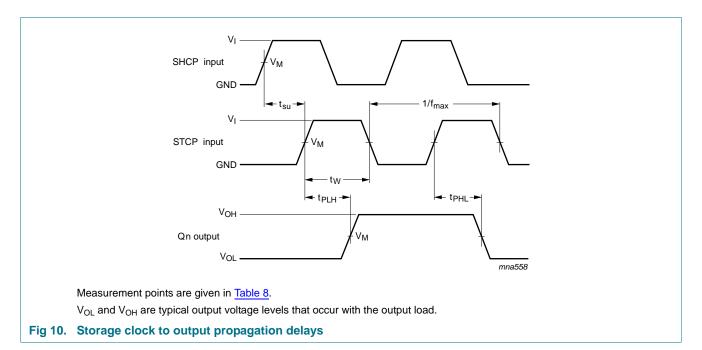
### 12. Waveforms

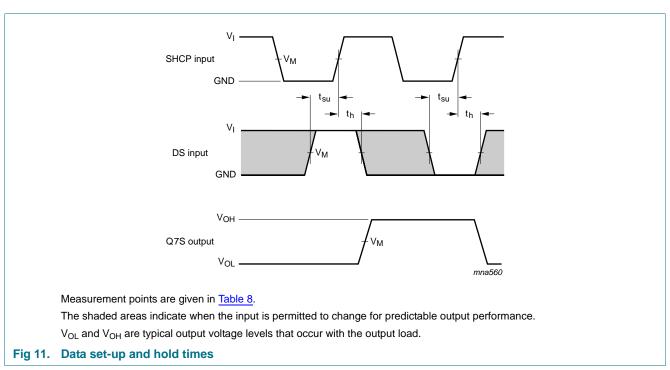


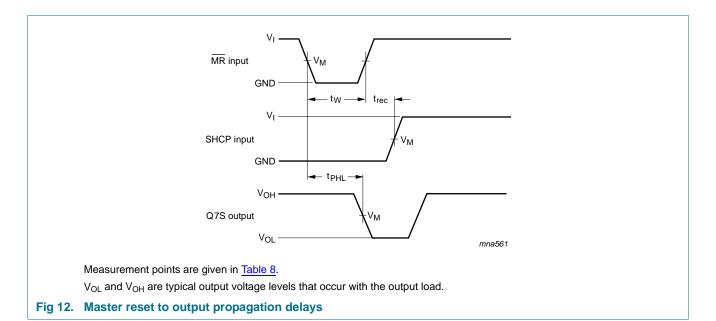
Measurement points are given in Table 8.

 $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

Fig 9. Shift clock pulse, maximum frequency and input to output propagation delays







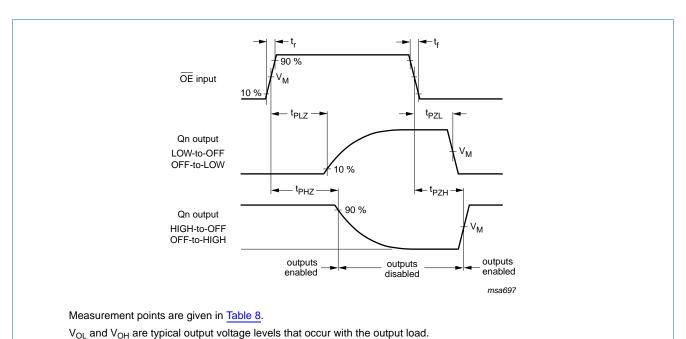
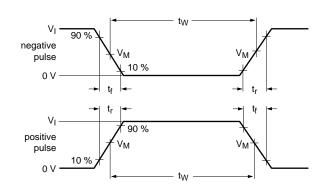


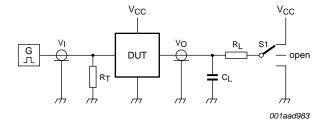
Fig 13. Enable and disable times

**Measurement points** 

Туре	Input	Output
	V <sub>M</sub>	V <sub>M</sub>
74HC595	0.5V <sub>CC</sub>	0.5V <sub>CC</sub>
74HCT595	1.3 V	1.3 V

Table 8.





Test data is given in Table 9.

Definitions for test circuit:

C<sub>L</sub> = load capacitance including jig and probe capacitance.

R<sub>L</sub> = load resistance.

 $R_T$  = termination resistance should be equal to the output impedance  $Z_0$  of the pulse generator.

S1 = test selection switch.

Fig 14. Test circuit for measuring switching times

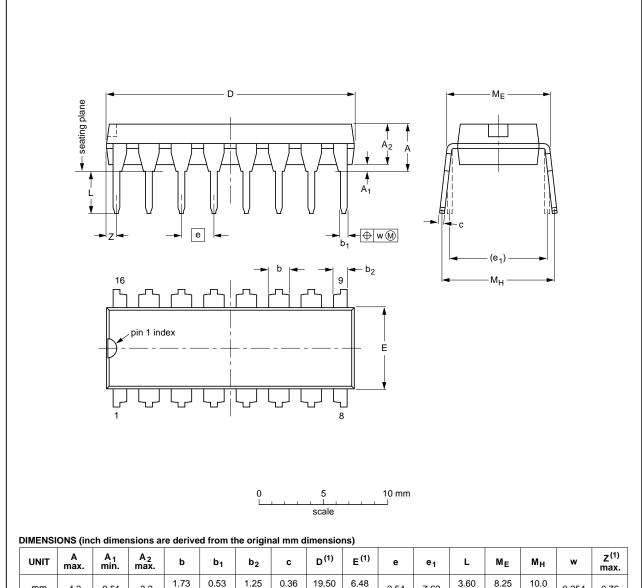
Table 9. Test data

Туре	Input	Input		S1 position			
	VI	t <sub>r</sub> , t <sub>f</sub>	CL	R <sub>L</sub>	t <sub>PHL</sub> , t <sub>PLH</sub>	t <sub>PZH</sub> , t <sub>PHZ</sub>	t <sub>PZL</sub> , t <sub>PLZ</sub>
74HC595	$V_{CC}$	6 ns	50 pF	1 kΩ	open	GND	V <sub>CC</sub>
74HCT595	3 V	6 ns	50 pF	1 kΩ	open	GND	$V_{CC}$

# 13. Package outline

#### DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4



UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	b <sub>2</sub>	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	e <sub>1</sub>	L	ME	Мн	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	1.25 0.85	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	0.76
inches	0.17	0.02	0.13	0.068 0.051	0.021 0.015	0.049 0.033	0.014 0.009	0.77 0.73	0.26 0.24	0.1	0.3	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.03

#### Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT38-4						<del>95-01-14</del> 03-02-13	

Fig 15. Package outline SOT38-4 (DIP16)

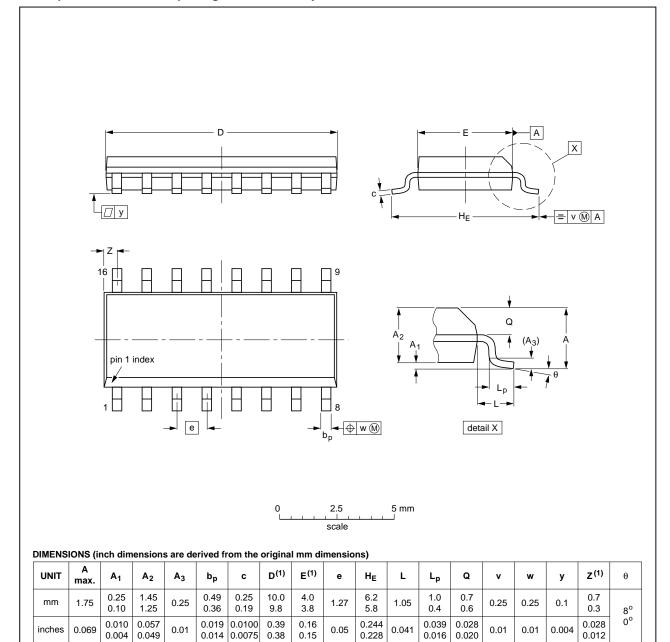
74HC\_HCT595

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SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



#### Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT109-1	076E07	MS-012				<del>99-12-27</del> 03-02-19	

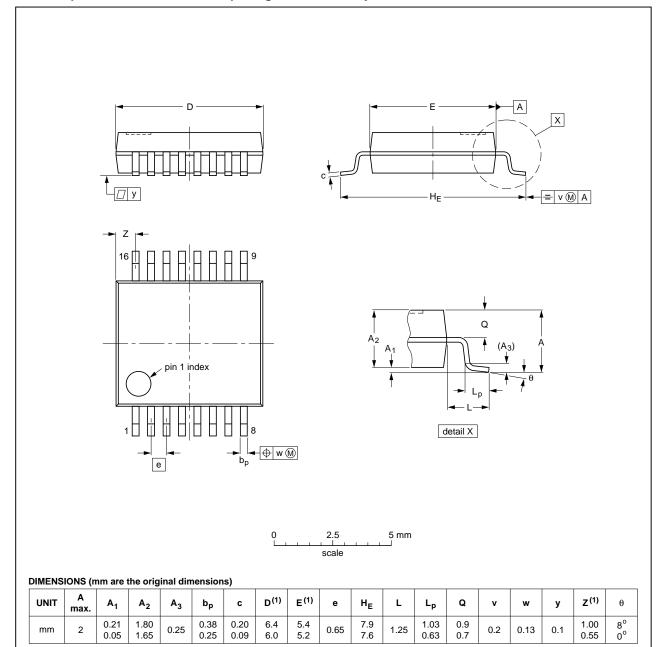
Fig 16. Package outline SOT109-1 (SO16)

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SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1



#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

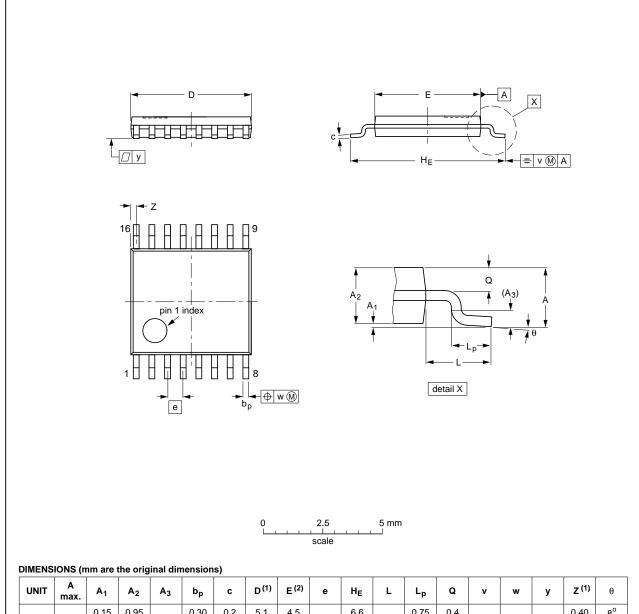
OUTLINE VERSION		REFER	EUROPEAN	ISSUE DATE		
	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT338-1		MO-150				<del>99-12-27</del> 03-02-19

Fig 17. Package outline SOT338-1 (SSOP16)

74HC\_HCT595

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1



UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	bp	С	D <sup>(1)</sup>	E <sup>(2)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.40 0.06	8° 0°

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	JEITA		PROJECTION	IGGGE DATE	
SOT403-1		MO-153				<del>99-12-27</del> 03-02-18	

Fig 18. Package outline SOT403-1 (TSSOP16)

74HC\_HCT595

DHVQFN16: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 x 3.5 x 0.85 mm SOT763-1

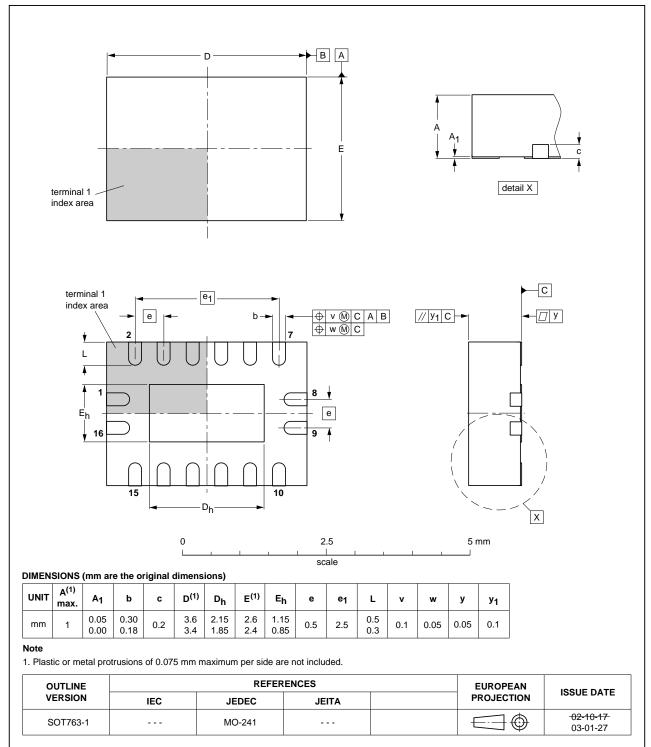


Fig 19. Package outline SOT763-1 (DHVQFN16)

74HC\_HCT595

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### 14. Abbreviations

#### Table 10. Abbreviations

Acronym	Abbreviation
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
LSTTL	Low-power Schottky Transistor-Transistor Logic
MM	Machine Model

# 15. Revision history

#### Table 11. Revision history

	-			
Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT595 v.6	20111212	Product data sheet	-	74HC_HCT595 v.5
Modifications:	<ul> <li>Legal pages</li> </ul>	updated.		
74HC_HCT595 v.5	20110628	Product data sheet	-	74HC_HCT595 v.4
74HC_HCT595 v.4	20030604	Product specification	-	74HC_HCT595_CNV v.3
74HC_HCT595_CNV v.3	19980604	Product specification	-	-

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Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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